

# IRFB3307PbF IRFS3307PbF IRFSL3307PbF

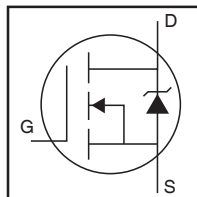
HEXFET® Power MOSFET

## Applications

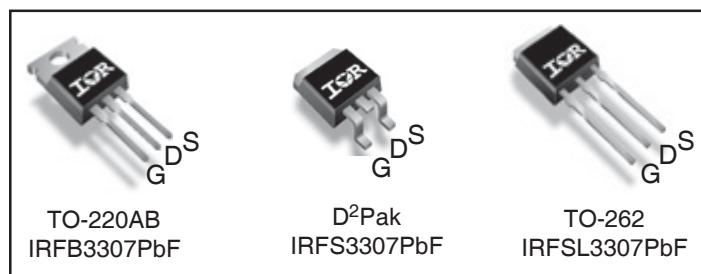
- High Efficiency Synchronous Rectification in SMPS
- Uninterruptible Power Supply
- High Speed Power Switching
- Hard Switched and High Frequency Circuits

## Benefits

- Improved Gate, Avalanche and Dynamic  $dV/dt$  Ruggedness
- Fully Characterized Capacitance and Avalanche SOA
- Enhanced body diode  $dV/dt$  and  $dI/dt$  Capability
- Lead-Free



|              |      |              |
|--------------|------|--------------|
| $V_{DSS}$    |      | <b>75V</b>   |
| $R_{DS(on)}$ | typ. | <b>5.0mΩ</b> |
|              | max. | <b>6.3mΩ</b> |
| $I_D$        |      | <b>120A</b>  |



## Absolute Maximum Ratings

| Symbol                            | Parameter  | Max.             | Units |
|-----------------------------------|--|------------------|-------|
| $I_D$ @ $T_C = 25^\circ\text{C}$  | Continuous Drain Current, $V_{GS}$ @ 10V                   | 120①②            | A     |
| $I_D$ @ $T_C = 100^\circ\text{C}$ | Continuous Drain Current, $V_{GS}$ @ 10V                   | 84①②             |       |
| $I_{DM}$                          | Pulsed Drain Current ②                                     | 510              |       |
| $P_D$ @ $T_C = 25^\circ\text{C}$  | Maximum Power Dissipation                                  | 200③             | W     |
|                                   | Linear Derating Factor                                     | 1.3③             | W/°C  |
| $V_{GS}$                          | Gate-to-Source Voltage                                     | ± 20             | V     |
| $T_J$<br>$T_{STG}$                | Operating Junction and<br>Storage Temperature Range        | -55 to + 175     | °C    |
|                                   | Soldering Temperature, for 10 seconds<br>(1.6mm from case) | 300              |       |
|                                   | Mounting torque, 6-32 or M3 screw                          | 10lb·in (1.1N·m) |       |

## Avalanche Characteristics

|                              |                                 |                           |    |
|------------------------------|---------------------------------|---------------------------|----|
| $E_{AS}$ (Thermally limited) | Single Pulse Avalanche Energy ③ | 270                       | mJ |
| $I_{AR}$                     | Avalanche Current ①             | See Fig. 14, 15, 16a, 16b | A  |
| $E_{AR}$                     | Repetitive Avalanche Energy ⑤   |                           | mJ |

## Thermal Resistance

| Symbol          | Parameter                                  | Typ. | Max.  | Units |
|-----------------|--|------|-------|-------|
| $R_{\theta JC}$ | Junction-to-Case ⑨                         | —    | 0.61⑩ | °C/W  |
| $R_{\theta CS}$ | Case-to-Sink, Flat Greased Surface, TO-220 | 0.50 | —     |       |
| $R_{\theta JA}$ | Junction-to-Ambient, TO-220 ⑨              | —    | 62    |       |
| $R_{\theta JA}$ | Junction-to-Ambient (PCB Mount), D²Pak ⑧⑨  | —    | 40    |       |

Static @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)

| Symbol                          | Parameter                            | Min. | Typ.  | Max. | Units               | Conditions   |
|---------------------------------|--------------------------------------|------|-------|------|---------------------|--|
| $V_{(BR)DSS}$                   | Drain-to-Source Breakdown Voltage    | 75   | —     | —    | V                   | $V_{GS} = 0V, I_D = 250\mu A$                          |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient  | —    | 0.069 | —    | V/ $^\circ\text{C}$ | Reference to $25^\circ\text{C}$ , $I_D = 1\text{mA}$ ② |
| $R_{DS(on)}$                    | Static Drain-to-Source On-Resistance | —    | 5.0   | 6.3  | m $\Omega$          | $V_{GS} = 10V, I_D = 75A$ ⑤                            |
| $V_{GS(th)}$                    | Gate Threshold Voltage               | 2.0  | —     | 4.0  | V                   | $V_{DS} = V_{GS}, I_D = 150\mu A$                      |
| $I_{DSS}$                       | Drain-to-Source Leakage Current      | —    | —     | 20   | $\mu A$             | $V_{DS} = 75V, V_{GS} = 0V$                            |
|                                 |                                      | —    | —     | 250  |                     | $V_{DS} = 75V, V_{GS} = 0V, T_J = 125^\circ\text{C}$   |
| $I_{GSS}$                       | Gate-to-Source Forward Leakage       | —    | —     | 200  | nA                  | $V_{GS} = 20V$   |
|                                 | Gate-to-Source Reverse Leakage       | —    | —     | -200 |                     | $V_{GS} = -20V$  |
| $R_G$                           | Gate Input Resistance                | —    | 1.5   | —    | $\Omega$            | $f = 1\text{MHz}$ , open drain                         |

Dynamic @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)

| Symbol                      | Parameter                                     | Min. | Typ. | Max. | Units | Conditions   |
|-----------------------------|---|------|------|------|-------|--|
| $g_{fs}$                    | Forward Transconductance                      | 98   | —    | —    | S     | $V_{DS} = 50V, I_D = 75A$                                |
| $Q_g$                       | Total Gate Charge                             | —    | 120  | 180  | nC    | $I_D = 75A$  |
| $Q_{gs}$                    | Gate-to-Source Charge                         | —    | 35   | —    |       | $V_{DS} = 60V$   |
| $Q_{gd}$                    | Gate-to-Drain ("Miller") Charge               | —    | 46   | —    |       | $V_{GS} = 10V$ ⑤   |
| $t_{d(on)}$                 | Turn-On Delay Time                            | —    | 26   | —    | ns    | $V_{DD} = 48V$   |
| $t_r$                       | Rise Time                                     | —    | 120  | —    |       | $I_D = 75A$  |
| $t_{d(off)}$                | Turn-Off Delay Time                           | —    | 51   | —    |       | $R_G = 3.9\Omega$  |
| $t_f$                       | Fall Time                                     | —    | 63   | —    |       | $V_{GS} = 10V$ ⑤   |
| $C_{iss}$                   | Input Capacitance                             | —    | 5150 | —    | pF    | $V_{GS} = 0V$  |
| $C_{oss}$                   | Output Capacitance                            | —    | 460  | —    |       | $V_{DS} = 50V$   |
| $C_{rss}$                   | Reverse Transfer Capacitance                  | —    | 250  | —    |       | $f = 1.0\text{MHz}$                                      |
| $C_{oss \text{ eff. (ER)}}$ | Effective Output Capacitance (Energy Related) | —    | 570  | —    |       | $V_{GS} = 0V, V_{DS} = 0V \text{ to } 60V$ ⑦, See Fig.11 |
| $C_{oss \text{ eff. (TR)}}$ | Effective Output Capacitance (Time Related)⑥  | —    | 700  | —    |       | $V_{GS} = 0V, V_{DS} = 0V \text{ to } 60V$ ⑧ See Fig. 5  |

## Diode Characteristics

| Symbol    | Parameter                                 | Min.   | Typ. | Max. | Units | Conditions  |
|-----------|---|--|------|------|-------|---|
| $I_S$     | Continuous Source Current<br>(Body Diode) | —  | —    | 130  | A     | MOSFET symbol<br>showing the<br>integral reverse<br>p-n junction diode. |
| $I_{SM}$  | Pulsed Source Current<br>(Body Diode) ②   | —  | —    | 510  | A     |   |
| $V_{SD}$  | Diode Forward Voltage                     | —  | —    | 1.3  | V     | $T_J = 25^\circ\text{C}, I_S = 75A, V_{GS} = 0V$ ⑤                      |
| $dv/dt$   | Peak Diode Recovery                       | —  | 11   | —    | V/ns  | $T_J = 175^\circ\text{C}, I_S = 75A, V_{DS} = 75V$ ④                    |
| $t_{rr}$  | Reverse Recovery Time                     | —  | 38   | 57   | ns    | $T_J = 25^\circ\text{C}$ $V_R = 64V,$                                   |
|           |   | —  | 46   | 69   |       | $T_J = 125^\circ\text{C}$ $I_F = 75A$                                   |
| $Q_{rr}$  | Reverse Recovery Charge                   | —  | 65   | 98   | nC    | $T_J = 25^\circ\text{C}$ $di/dt = 100A/\mu s$ ⑤                         |
|           |   | —  | 86   | 130  |       | $T_J = 125^\circ\text{C}$   |
| $I_{RRM}$ | Reverse Recovery Current                  | —  | 2.8  | —    | A     | $T_J = 25^\circ\text{C}$  |
| $t_{on}$  | Forward Turn-On Time                      | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) |      |      |       |   |

## Notes:

- ① Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ Limited by  $T_{Jmax}$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.096\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = 75A$ ,  $V_{GS} = 10V$ . Part not recommended for use above this value.
- ④  $I_{SD} \leq 75A$ ,  $di/dt \leq 530A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq 175^\circ\text{C}$ .
- ⑤ Pulse width  $\leq 400\mu s$ ; duty cycle  $\leq 2\%$ .
- ⑥  $C_{oss \text{ eff. (TR)}}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .
- ⑦  $C_{oss \text{ eff. (ER)}}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .
- ⑧ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.
- ⑨  $R_\theta$  is measured at  $T_J$  approximately  $90^\circ\text{C}$ .
- ⑩  $R_{\theta JC}$  (end of life) for D<sup>2</sup>Pak and TO-262 =  $0.75^\circ\text{C/W}$ . Note: This is the maximum measured value after 1000 temperature cycles from  $-55$  to  $150^\circ\text{C}$  and is accounted for by the physical wearout of the die attach medium.

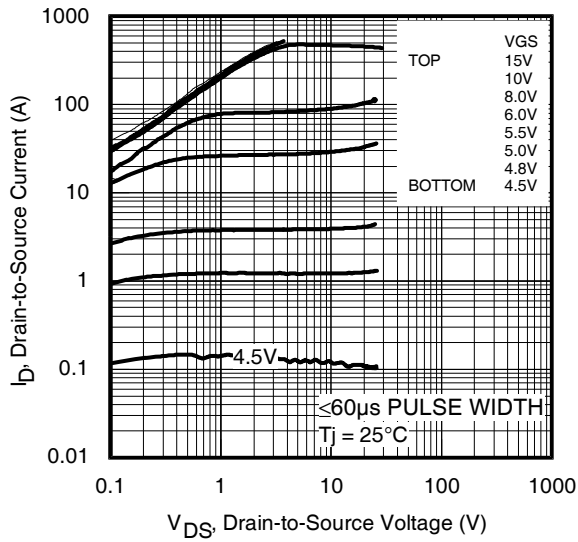


Fig 1. Typical Output Characteristics

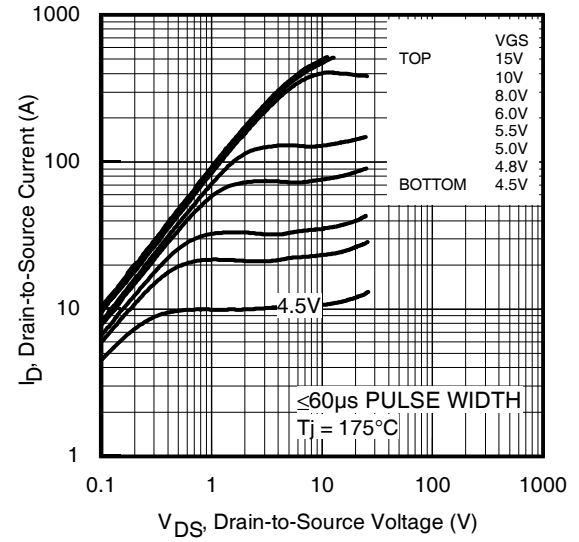


Fig 2. Typical Output Characteristics

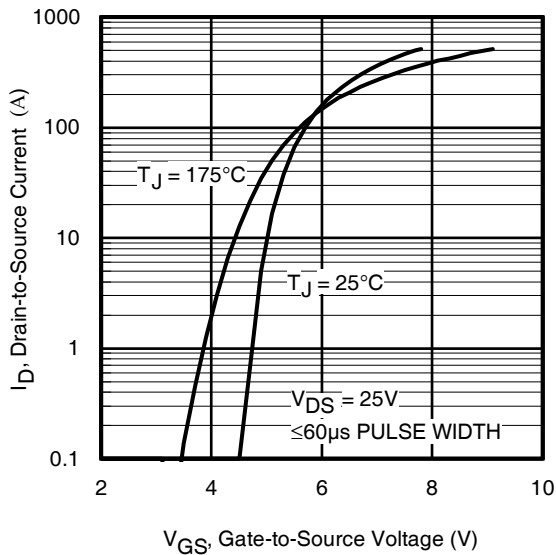


Fig 3. Typical Transfer Characteristics

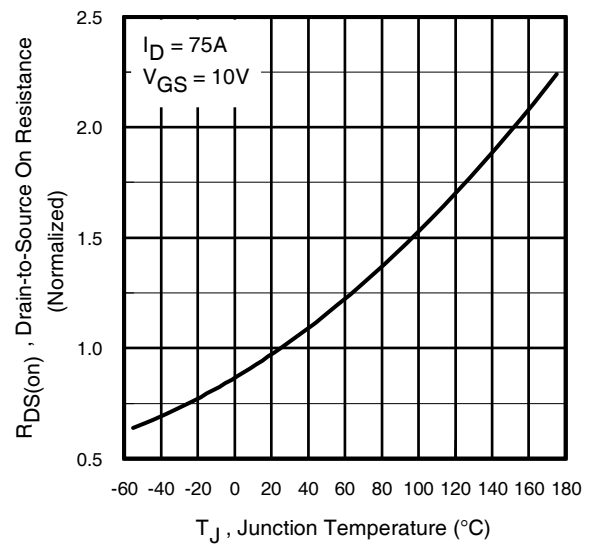


Fig 4. Normalized On-Resistance vs. Temperature

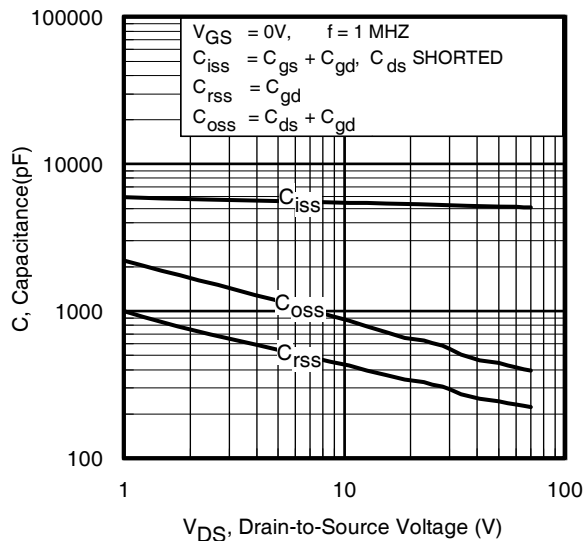


Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

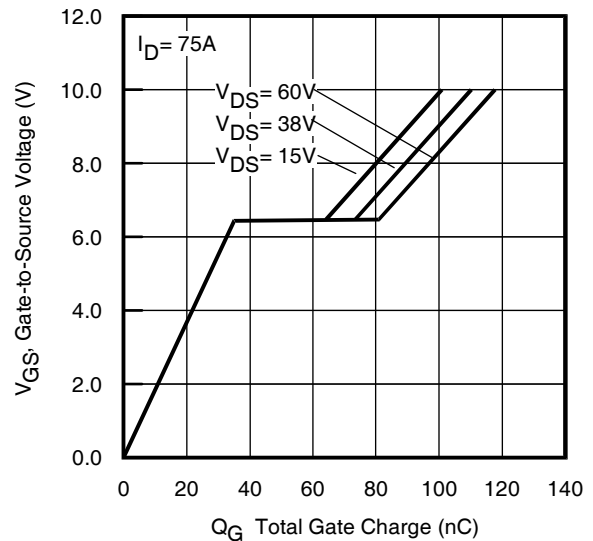
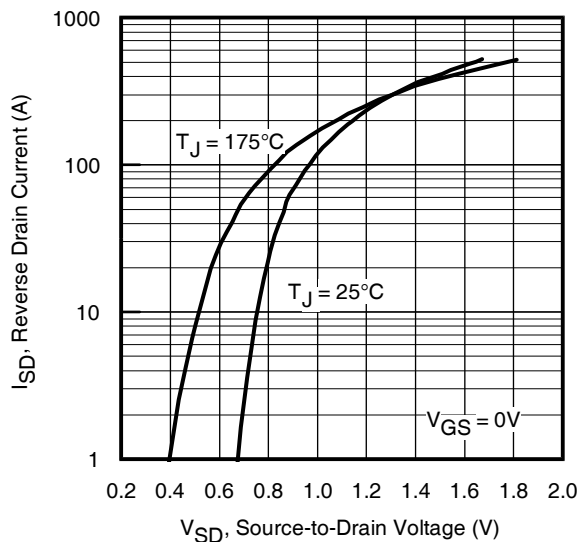
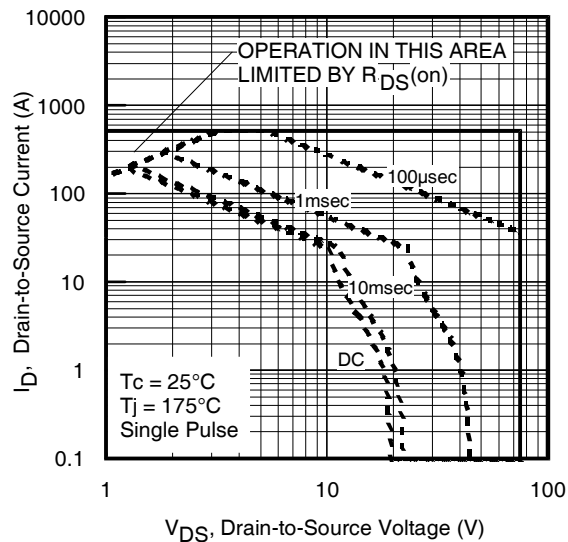


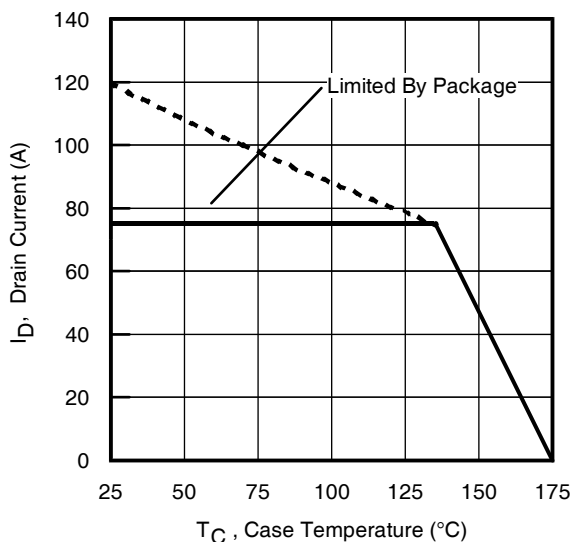
Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage



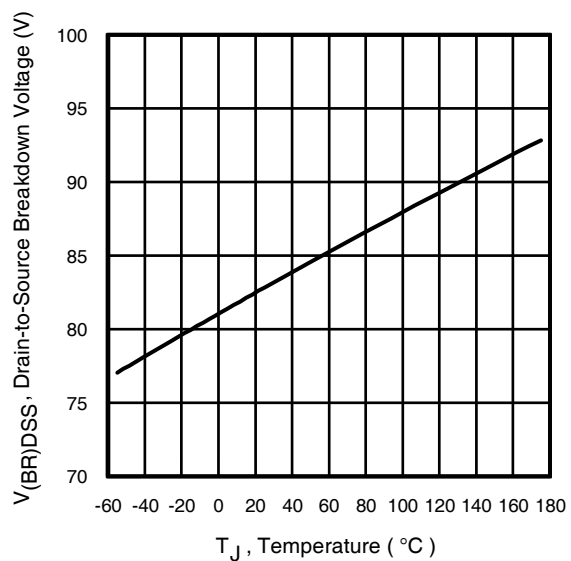
**Fig 7.** Typical Source-Drain Diode Forward Voltage



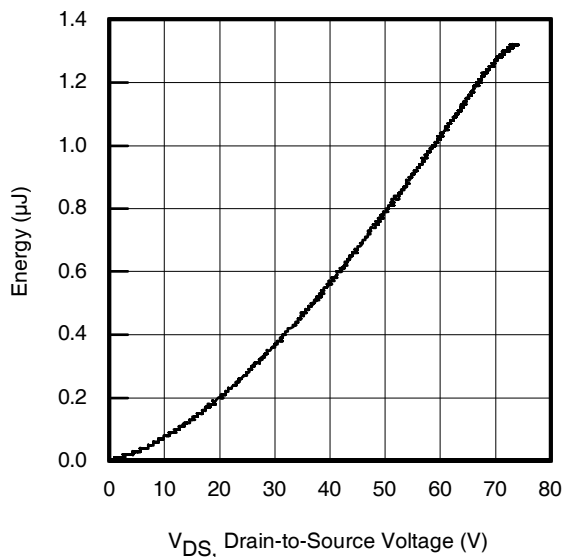
**Fig 8.** Maximum Safe Operating Area



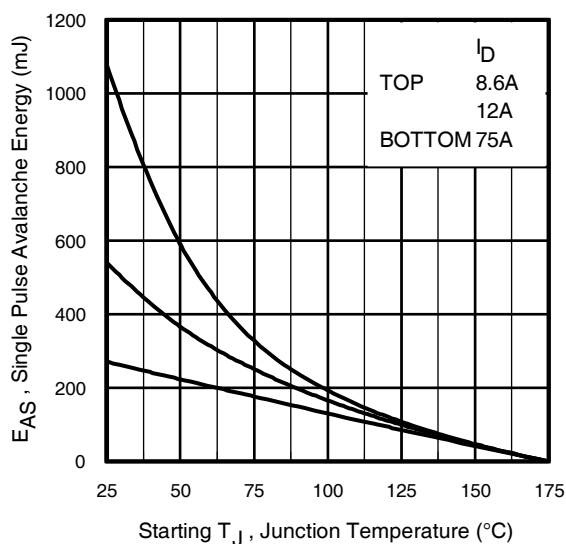
**Fig 9.** Maximum Drain Current vs. Case Temperature



**Fig 10.** Drain-to-Source Breakdown Voltage



**Fig 11.** Typical  $C_{OSS}$  Stored Energy



**Fig 12.** Maximum Avalanche Energy vs. Drain Current

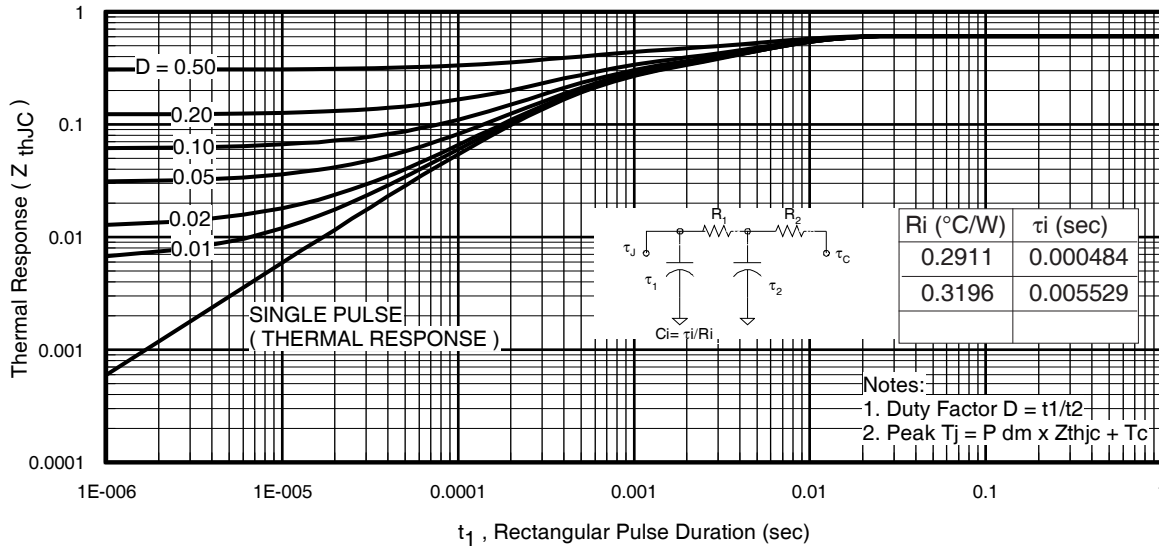


Fig 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

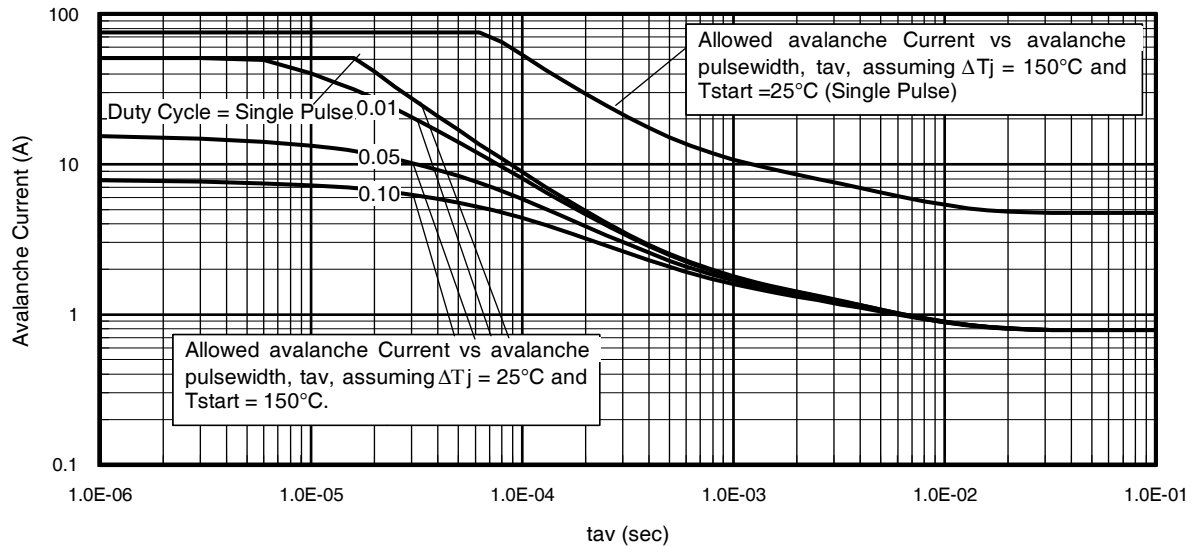


Fig 14. Typical Avalanche Current vs. Pulsewidth

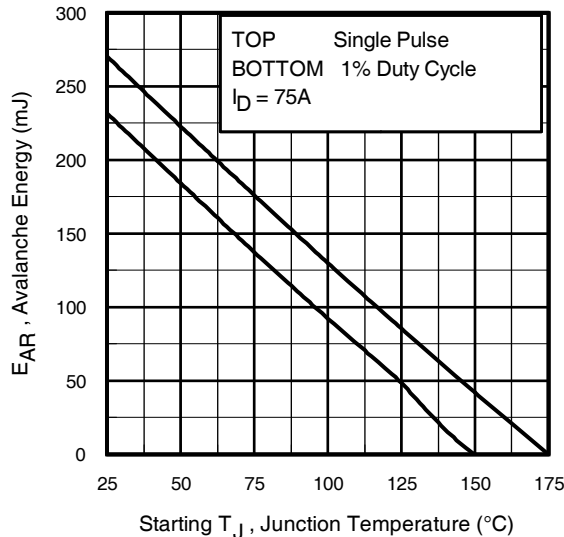


Fig 15. Maximum Avalanche Energy vs. Temperature

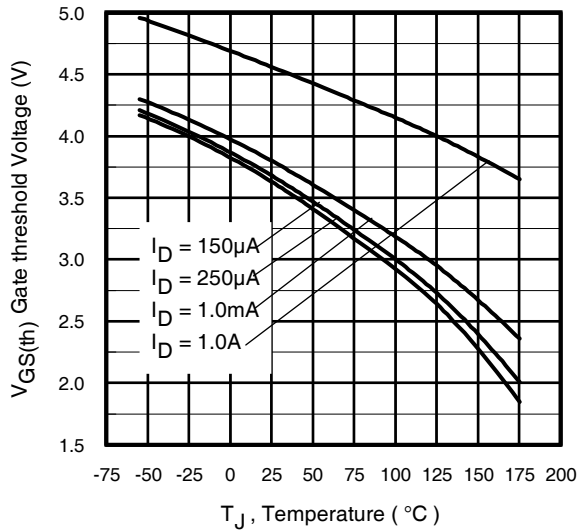
Notes on Repetitive Avalanche Curves, Figures 14, 15:  
(For further info, see AN-1005 at [www.irf.com](http://www.irf.com))

- Avalanche failures assumption:  
Purely a thermal phenomenon and failure occurs at a temperature far in excess of  $T_{jmax}$ . This is validated for every part type.
- Safe operation in Avalanche is allowed as long as neither  $T_{jmax}$  nor  $I_{av(max)}$  is exceeded.
- Equation below based on circuit and waveforms shown in Figures 16a, 16b.
- $P_{D(ave)}$  = Average power dissipation per single avalanche pulse.
- $BV$  = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
- $I_{av}$  = Allowable avalanche current.
- $\Delta T$  = Allowable rise in junction temperature, not to exceed  $T_{jmax}$  (assumed as  $25^{\circ}\text{C}$  in Figure 14, 15).  
 $t_{av}$  = Average time in avalanche.  
 $D$  = Duty cycle in avalanche =  $t_{av} \cdot f$   
 $Z_{thJC}(D, t_{av})$  = Transient thermal resistance, see Figures 13)

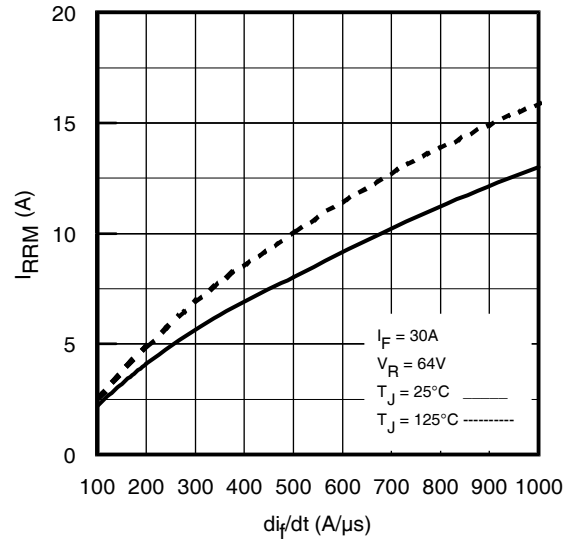
$$P_{D(ave)} = 1/2 (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$

$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{thJC}]$$

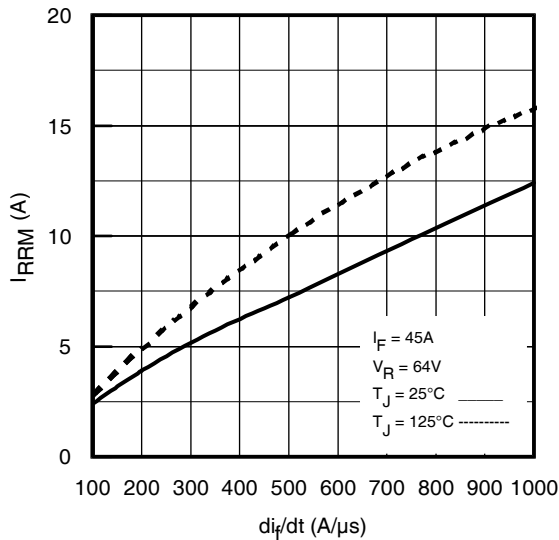
$$E_{AS(AR)} = P_{D(ave)} \cdot t_{av}$$



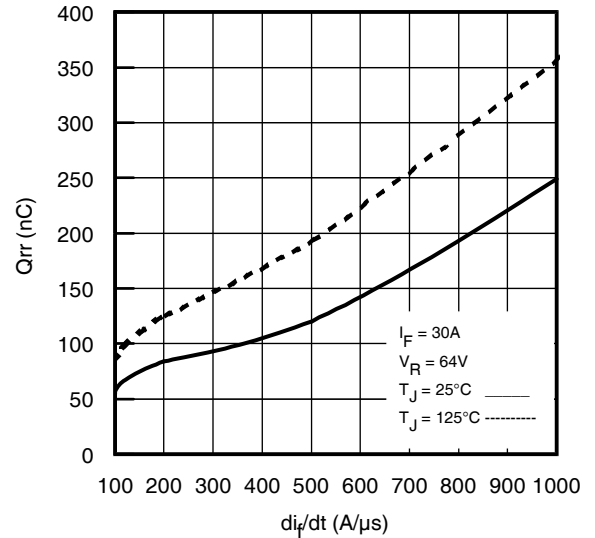
**Fig. 16.** Threshold Voltage vs. Temperature



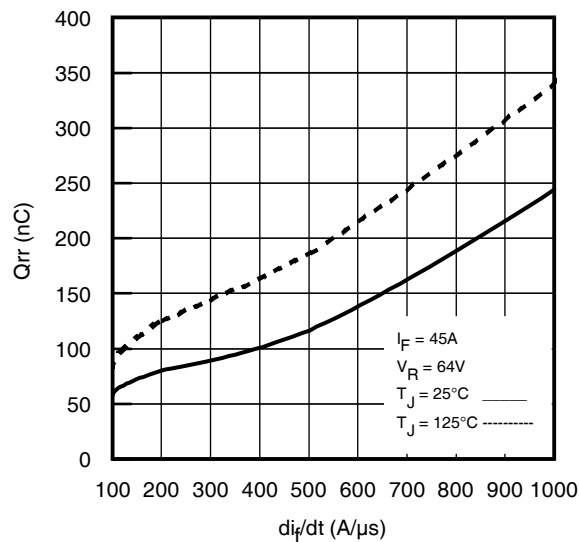
**Fig. 17 -** Typical Recovery Current vs.  $di_T/dt$



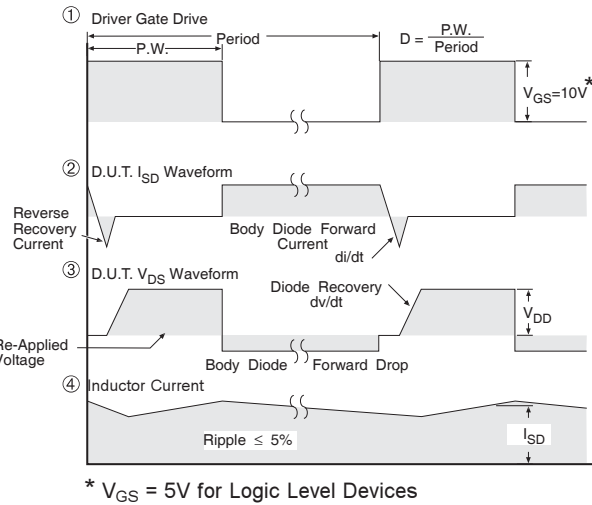
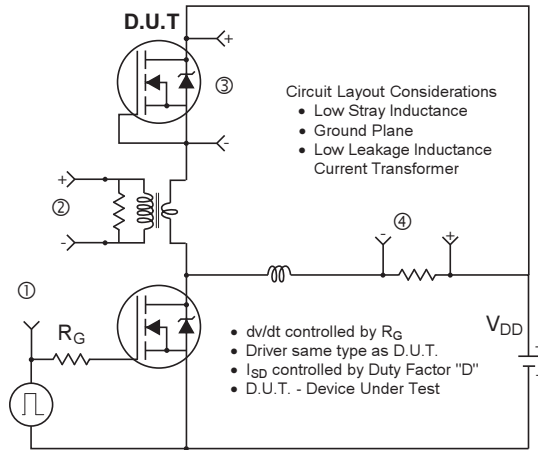
**Fig. 18 -** Typical Recovery Current vs.  $di_T/dt$



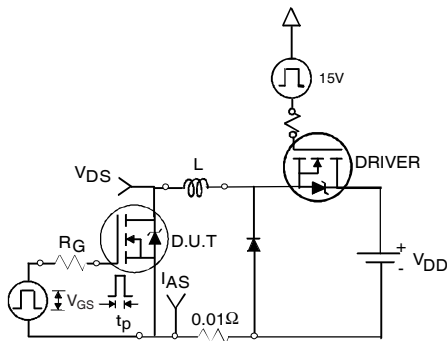
**Fig. 19 -** Typical Stored Charge vs.  $di_T/dt$



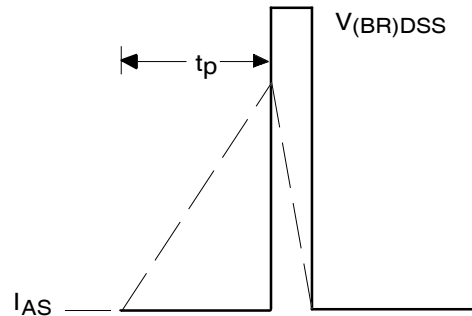
**Fig. 20 -** Typical Stored Charge vs.  $di_T/dt$



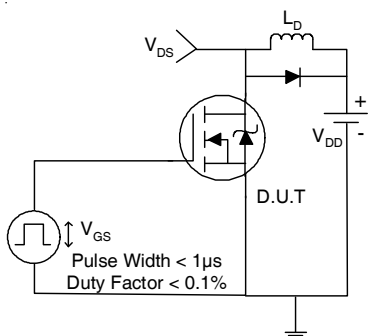
**Fig 20. Peak Diode Recovery  $dv/dt$  Test Circuit for N-Channel HEXFET® Power MOSFETs**



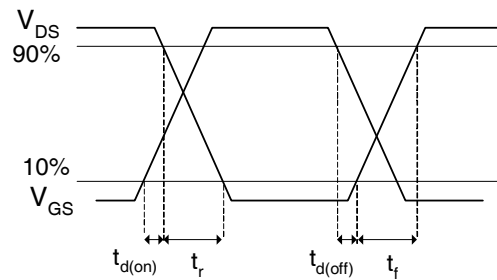
**Fig 21a. Unclamped Inductive Test Circuit**



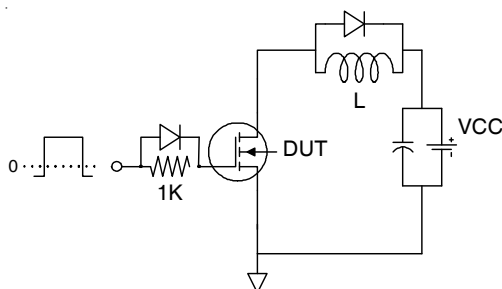
**Fig 21b. Unclamped Inductive Waveforms**



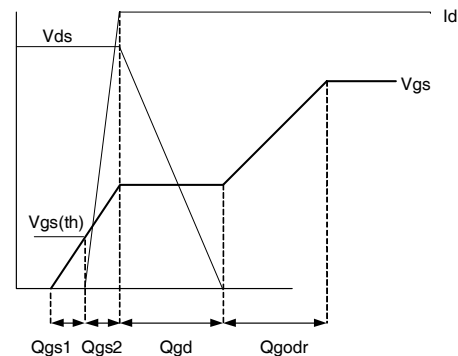
**Fig 22a. Switching Time Test Circuit**



**Fig 22b. Switching Time Waveforms**

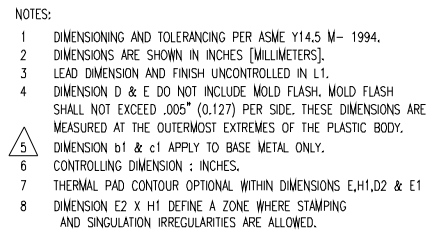


**Fig 23a. Gate Charge Test Circuit**



**Fig 23b. Gate Charge Waveform**

Dimensions are shown in millimeters (inches)



| SYMBOL | DIMENSIONS  |       |          |      | NOTES |
|--------|-------------|-------|----------|------|-------|
|        | MILLIMETERS |       | INCHES   |      |       |
|        | MIN.        | MAX.  | MIN.     | MAX. |       |
| A      | 3.56        | 4.82  | .140     | .190 | 5     |
| A1     | 0.51        | 1.40  | .020     | .055 |       |
| A2     | 2.04        | 2.92  | .080     | .115 |       |
| b      | 0.38        | 1.01  | .015     | .040 |       |
| b1     | 0.38        | 0.96  | .015     | .038 |       |
| b2     | 1.15        | 1.77  | .045     | .070 | 5     |
| b3     | 1.15        | 1.73  | .045     | .068 |       |
| c      | 0.36        | 0.61  | .014     | .024 |       |
| c1     | 0.36        | 0.56  | .014     | .022 |       |
| D      | 14.22       | 16.51 | .560     | .650 |       |
| D1     | 8.38        | 9.02  | .330     | .355 | 7     |
| D2     | 12.19       | 12.88 | .480     | .507 |       |
| E      | 9.66        | 10.66 | .380     | .420 |       |
| E1     | 8.38        | 8.89  | .330     | .350 | 7     |
| e      | 2.54 BSC    |       | .100 BSC |      | 7,8   |
| e1     | 5.08        |       | .200 BSC |      |       |
| H1     | 5.85        | 6.55  | .230     | .270 |       |
| L      | 12.70       | 14.73 | .500     | .580 |       |
| L1     | -           | 6.35  | -        | .250 |       |
| øP     | 3.54        | 4.08  | .139     | .161 |       |
| Q      | 2.54        | 3.42  | .100     | .135 |       |
| ø      | 90°-93°     |       | 90°-93°  |      |       |

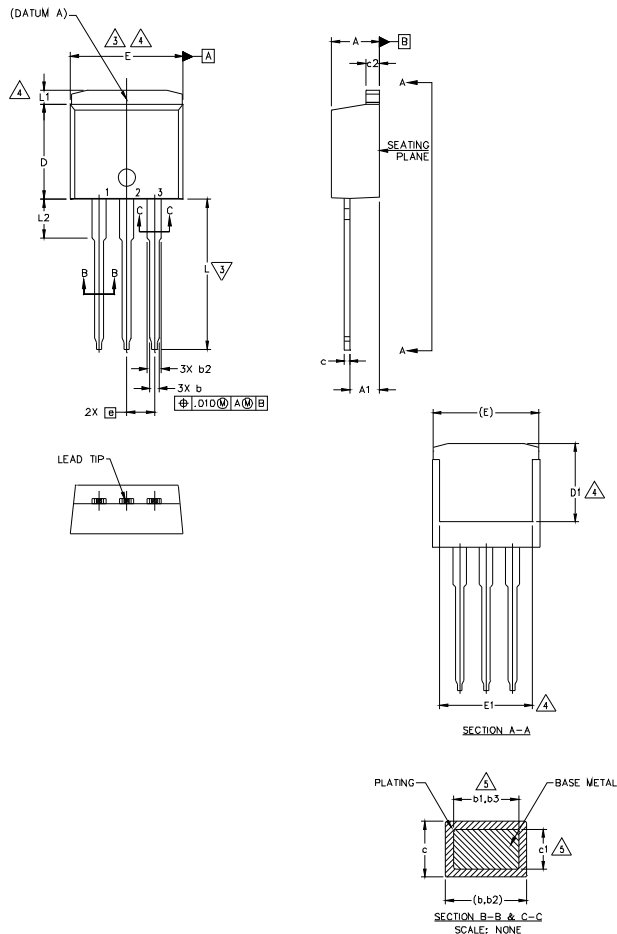
- 1.- ANODE/OPEN
- 2.- CATHODE
- 3.- ANODE

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## TO-262 Package Outline

Dimensions are shown in millimeters (inches)



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [0.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION: INCH.
7. OUTLINE CONFORM TO JEDEC TO-262 EXCEPT A1(max.), b(min.) AND D1(min.) WHERE DIMENSIONS DERIVED THE ACTUAL PACKAGE OUTLINE.

| SYMBOL | DIMENSIONS  |       |          |      | NOTES |
|--------|-------------|-------|----------|------|-------|
|        | MILLIMETERS |       | INCHES   |      |       |
|        | MIN.        | MAX.  | MIN.     | MAX. |       |
| A      | 4.06        | 4.83  | .160     | .190 |       |
| A1     | 2.03        | 3.02  | .080     | .119 |       |
| b      | 0.51        | 0.99  | .020     | .039 |       |
| b1     | 0.51        | 0.89  | .020     | .035 | 5     |
| b2     | 1.14        | 1.78  | .045     | .070 |       |
| b3     | 1.14        | 1.73  | .045     | .068 | 5     |
| c      | 0.38        | 0.74  | .015     | .029 |       |
| c1     | 0.38        | 0.58  | .015     | .023 | 5     |
| c2     | 1.14        | 1.65  | .045     | .065 |       |
| D      | 8.38        | 9.65  | .330     | .380 | 3     |
| D1     | 6.86        | —     | .270     | —    | 4     |
| E      | 9.65        | 10.67 | .380     | .420 | 3, 4  |
| E1     | 6.22        | —     | .245     | —    |       |
| e      | 2.54 BSC    |       | .100 BSC |      |       |
| L      | 13.46       | 14.10 | .530     | .555 |       |
| L1     | —           | 1.65  | —        | .065 | 4     |
| L2     | 3.56        | 3.71  | .140     | .146 |       |

### LEAD ASSIGNMENTS

#### HEXFET

- 1.— GATE
- 2.— DRAIN
- 3.— SOURCE
- 4.— DRAIN

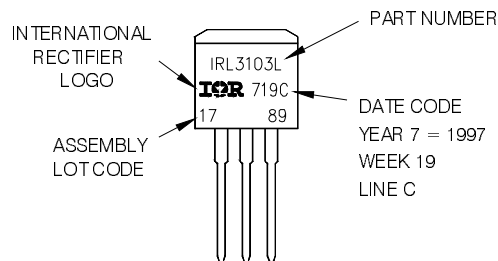
#### IGBTs, CoPACK

- 1.— GATE
- 2.— COLLECTOR
- 3.— EMITTER
- 4.— COLLECTOR

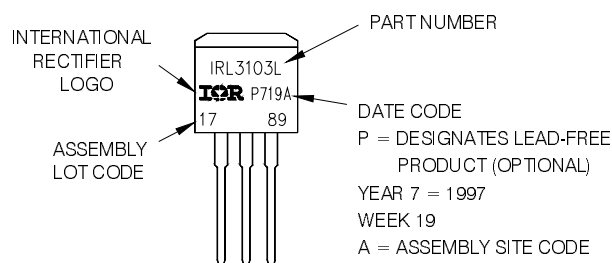
## TO-262 Part Marking Information

EXAMPLE: THIS IS AN IRL3103L  
LOT CODE 1789  
ASSEMBLED ON WW 19, 1997  
IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line position  
indicates "Lead - Free"

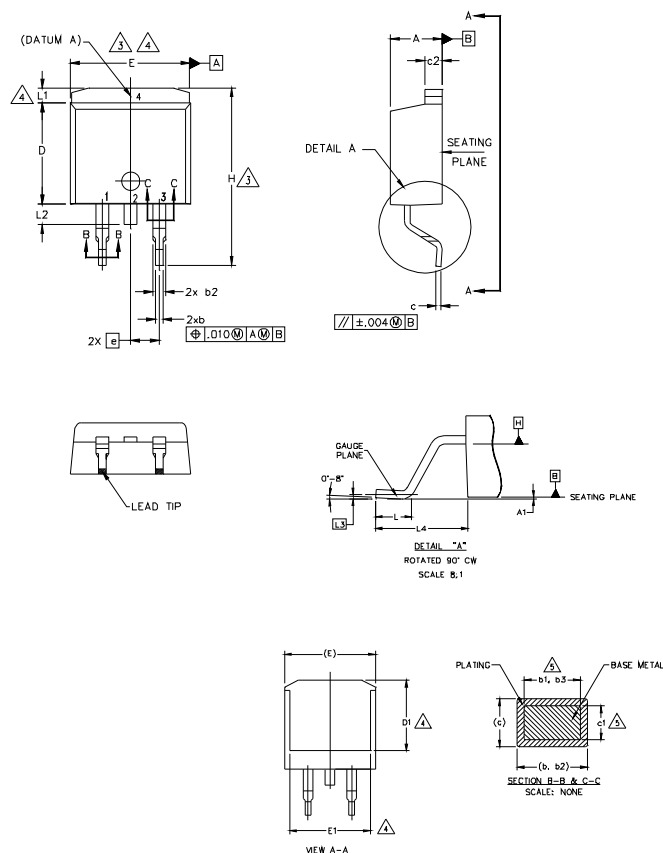


OR



## D<sup>2</sup>Pak (TO-263AB) Package Outline

Dimensions are shown in millimeters (inches)



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [0.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
7. CONTROLLING DIMENSION: INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-263AB.

| SYMBOL | DIMENSIONS  |       |          |      | NOTES |
|--------|-------------|-------|----------|------|-------|
|        | MILLIMETERS |       | INCHES   |      |       |
|        | MIN.        | MAX.  | MIN.     | MAX. |       |
| A      | 4.06        | 4.83  | .160     | .190 | 5     |
| A1     | 0.00        | 0.254 | .000     | .010 |       |
| b      | 0.51        | 0.99  | .020     | .039 |       |
| b1     | 0.51        | 0.89  | .020     | .035 |       |
| b2     | 1.14        | 1.78  | .045     | .070 | 5     |
| b3     | 1.14        | 1.73  | .045     | .068 |       |
| c      | 0.38        | 0.74  | .015     | .029 |       |
| c1     | 0.38        | 0.58  | .015     | .023 |       |
| c2     | 1.14        | 1.65  | .045     | .065 | 3     |
| D      | 8.38        | 9.65  | .330     | .380 |       |
| D1     | 6.86        | —     | .270     | —    |       |
| E      | 9.65        | 10.67 | .380     | .420 |       |
| E1     | 6.22        | —     | .245     | —    | 3,4   |
| e      | 2.54 BSC    |       | .100 BSC |      | 4     |
| H      | 14.61       | 15.88 | .575     | .625 |       |
| L      | 1.78        | 2.79  | .070     | .110 |       |
| L1     | —           | 1.65  | —        | .066 |       |
| L2     | 1.27        | 1.78  | —        | .070 | 4     |
| L3     | 0.25 BSC    |       | .010 BSC |      |       |
| L4     | 4.78        | 5.28  | .188     | .208 |       |

### LEAD ASSIGNMENTS

#### HEXFET

1. GATE
2. DRAIN
3. SOURCE

#### IGBTs, CoPACK

1. GATE
- 2, 4. COLLECTOR
3. EMITTER

#### DIODES

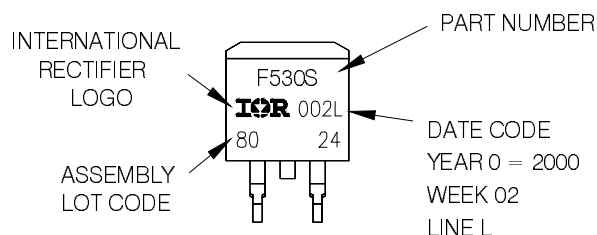
1. ANODE \*
2. CATHODE
3. ANODE

\* PART DEPENDENT.

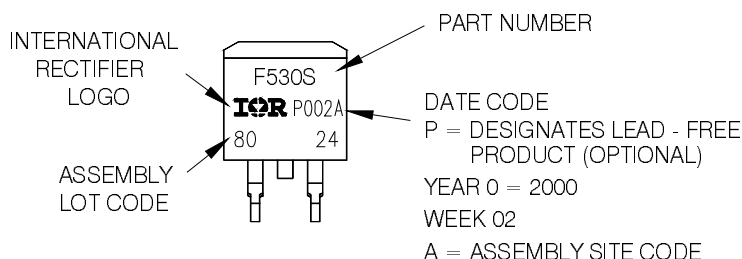
## D<sup>2</sup>Pak (TO-263AB) Part Marking Information

EXAMPLE: THIS IS AN IRF530S WITH  
LOT CODE 8024  
ASSEMBLED ON WW 02, 2000  
IN THE ASSEMBLY LINE "L"

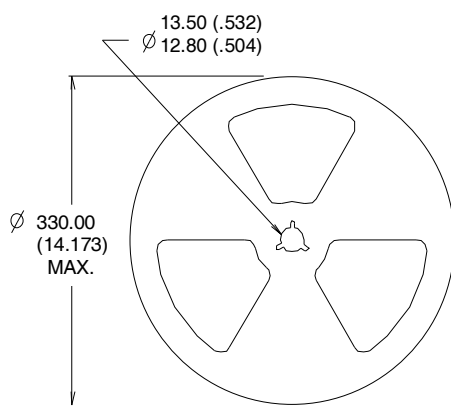
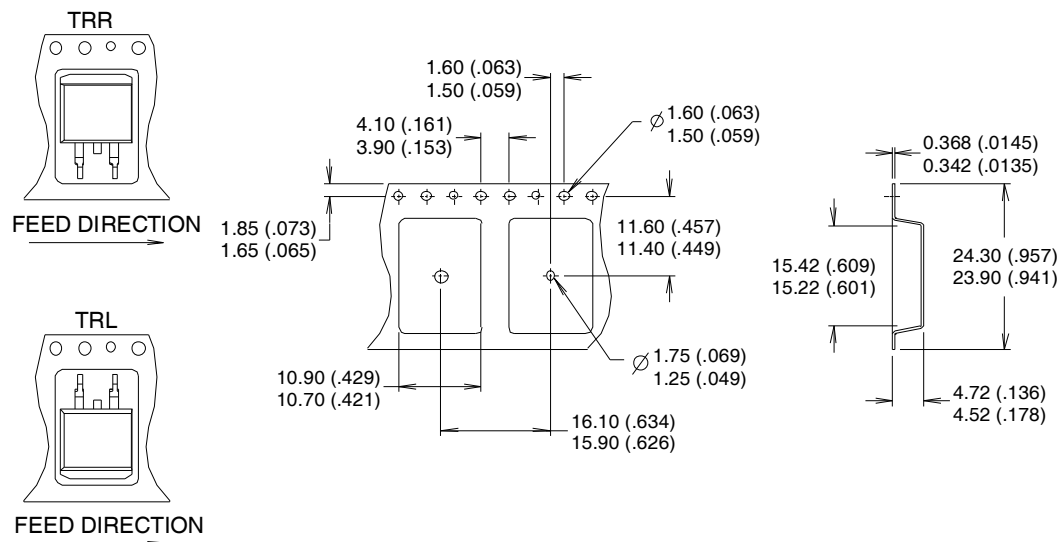
Note: "P" in assembly line position  
indicates "Lead - Free"



OR

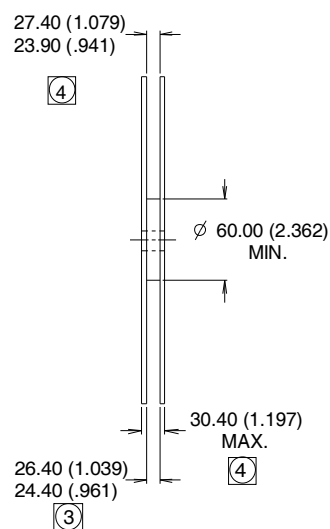


## D<sup>2</sup>Pak (TO-263AB) Tape & Reel Information



### NOTES :

1. COMFORMS TO EIA-418.
2. CONTROLLING DIMENSION: MILLIMETER.
- ③ DIMENSION MEASURED @ HUB.
- ④ INCLUDES FLANGE DISTORTION @ OUTER EDGE.



Data and specifications subject to change without notice.  
This product has been designed and qualified for the Industrial market.  
Qualification Standards can be found on IR's Web site.

International  
IOR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
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